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Part Number: [0545482071](#)
Status: **Active**
Overview: [ffc_fpc_smt](#)
Description: 0.50mm (.020") Pitch FFC/FPC Connector, 1.20mm (.047") Height, Right Angle, SMT, ZIF, Bottom Contact Style, 20 Circuits, Lead-free, Gold Contact Plating

Documents:

3D Model	Product Specification PS-54548-039 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

General

Product Family	FFC/FPC Connectors
Series	54548
Overview	ffc_fpc_smt
Product Name	N/A

Physical

Circuits (Loaded)	20
Contact Position	Bottom
Durability (mating cycles max)	20
Entry Angle	90° Angle
Mated Height (in)	0.047 In
Mated Height (mm)	1.20 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-20°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC

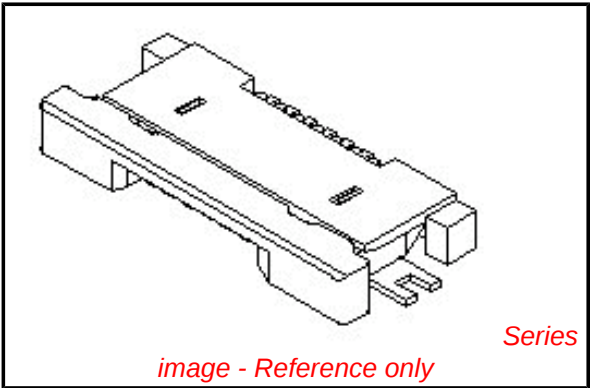
Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers

Packaging Specification	SPK-54548-001
Product Specification	PS-54548-039, RPS-54548-083, RPS-54548-085, RPS-54548-091, RPS-54548-092, RPS-54548-097, RPS-54548-099
Sales Drawing	SD-54548-039, SD-54548-040



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Not Reviewed
**Halogen-Free
Status**
Not Reviewed

China RoHS

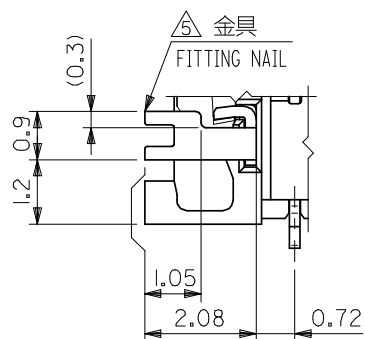
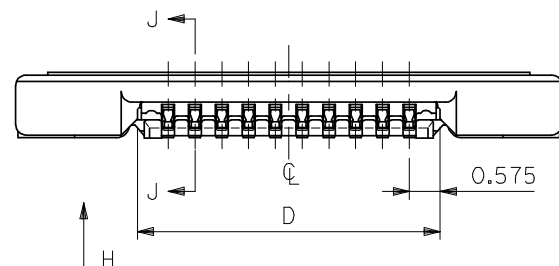
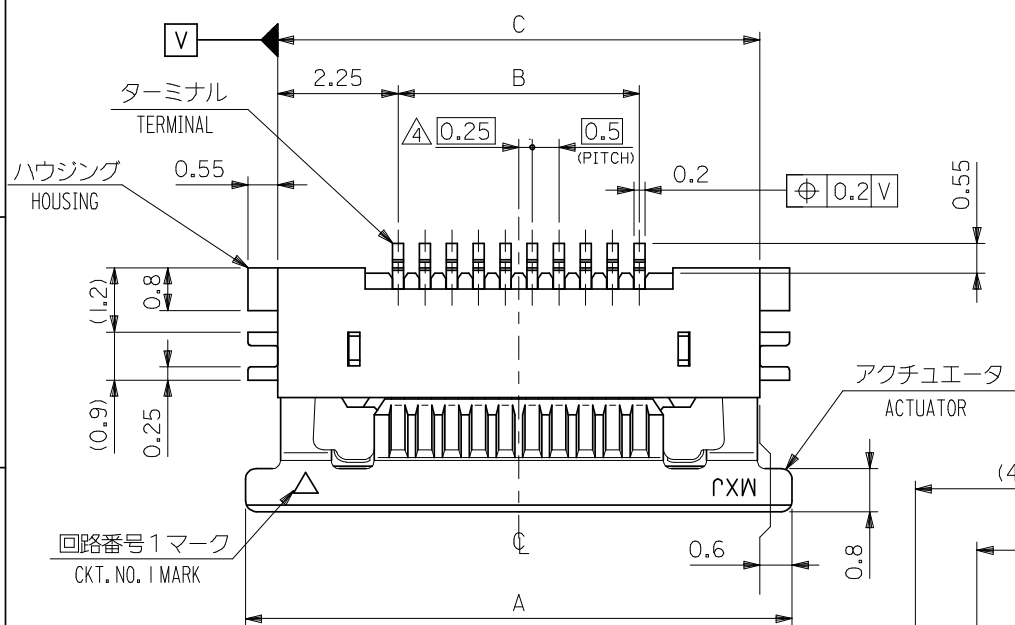


**Need more information on product
environmental compliance?**

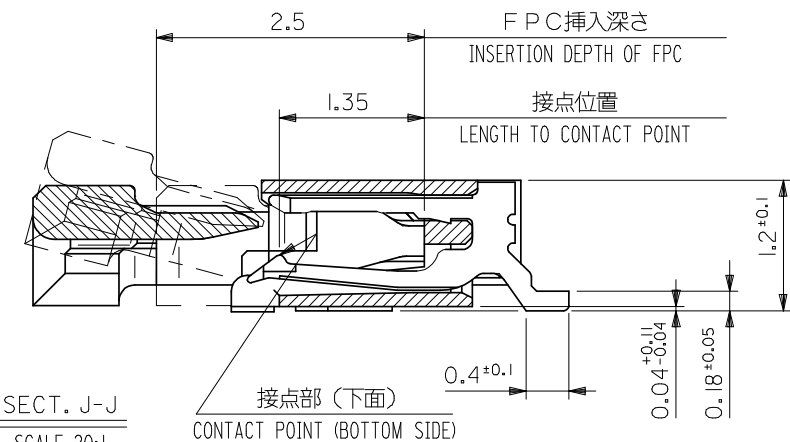
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[54548Series](#)



VIEW H



SECT. J-J
SCALE 20:1

0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24
0.3±0.03	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14
	7.15	10.5	6.0	11.7	54548-1371	54548-1329	13
	6.65	10.0	5.5	11.2	54548-1271	54548-1229	12
	6.15	9.5	5.0	10.7	54548-1171	54548-1129	11
	5.65	9.0	4.5	10.2	54548-1071	54548-1029	10
	5.15	8.5	4.0	9.7	54548-0971	54548-0929	9
	4.65	8.0	3.5	9.2	54548-0871	54548-0829	8
	4.15	7.5	3.0	8.7	54548-0771	54548-0729	7
	3.65	7.0	2.5	8.2	54548-0671	54548-0629	6
	3.15	6.5	2.0	7.7	54548-0571	54548-0529	5
	2.65	6.0	1.5	7.2	54548-0471	54548-0429	4
FPC THICKNESS	D	C	B	A	EMBOSSD TAPE ORDER No. オーダー番号	製品番号 MATERIAL No.	極数 Ck+

54548-**29	MODEL No.
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DESIGN UNITS	THIRD ANGLE
METRIC	PROJECTION

0.5 FPC CONN ZIF HSG
ASSY FOR SMT RA BTM CONT
-LEAD FREE-

 MOLEX INCORPORATED

DOCUMENT NO. SD-54548-039	SHEET NO. 1 OF 2
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REVISED	EC NO: J2008-4048	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	DRWN:WABEI		10 UNDER	± 0.2
	CH'KD: THIRUYAMA		10 OVER 30 UNDER	± 0.25
	APPR: NUKITA		30 OVER	± 0.3
			ANGULAR	± 3 °
		REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

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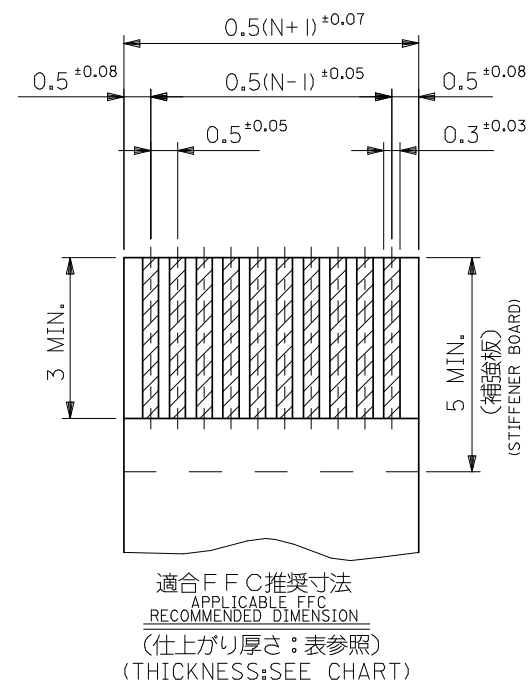
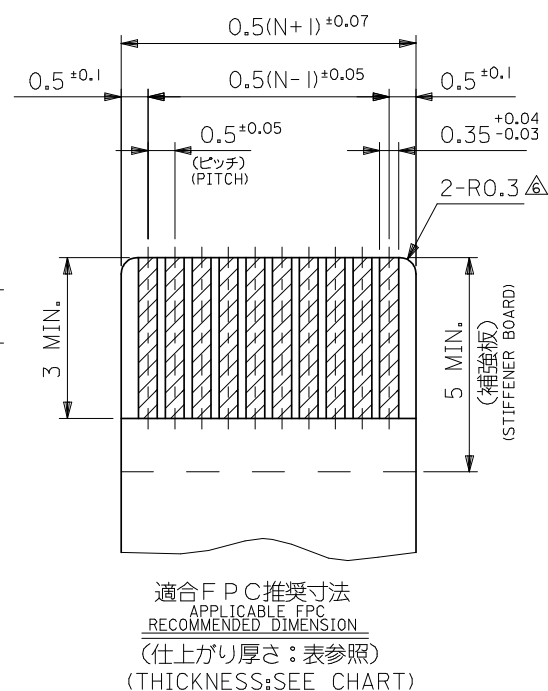
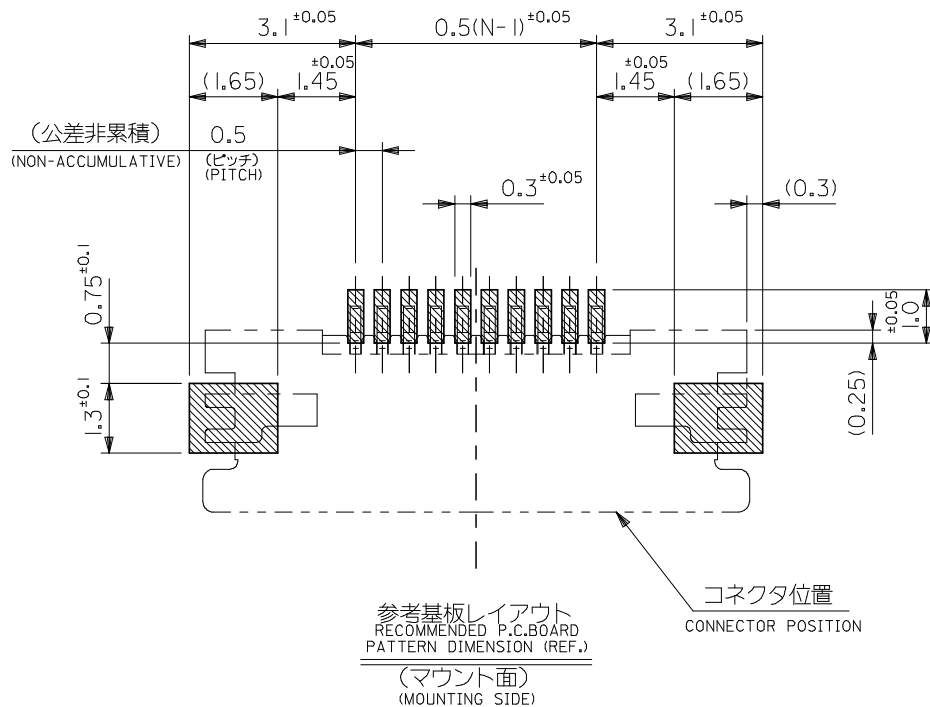
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注記 NOTES

I. 使用材料 MATERIAL

ハウジング : LCP, UL94V-0
ハウジング
アクチュエータ : PPS, UL94V-0
アクチュエータ
ターミナル : リン青銅 (t=0.2)
ターミナル
メッキ : PHOSPOR BRONZE
メッキ
接点部 : 金メッキ
CONTACT PORTION : GOLD PLATING
テール部 : 鍍メッキ
SOLDERING PORTION : TIN OVER PLATING
下地 : ニッケルメッキ
UNDER PLATING: NICKEL PLATING
金具 : リン青銅、鍍メッキ (t=0.2)
FITTING NAIL : PHOSPOR BRONZE, TIN PLATING
下地 : ニッケルメッキ
UNDER PLATING: NICKEL PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 54548-**-29 SHOULD BE LOCKED.
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 0 MAX.、下方向 0.15 MAX. とし
相互のバツキ量は 0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.

偶数極に適用。
APPLY FOR EVEN CIRCUIT.

パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
RO.3 は FPC 導体部にかからないこと
RO.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. 本製品は 54548-**-21 の鉛フリー (部分金メッキ) 品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-21 (SELECTIVE GOLD).
8. N: 極数 N: CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔 35 μm または 50 μm を推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは 25 μm を推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25 μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN: WABEI CHKD: THARUYAMA APPR: NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	54548-**-29	MODEL No.	
		10 UNDER ±0.2		DRAWN BY DATE HSHIMABUKURO '04/02/10		TITLE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE KTOJO '04/02/10		0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
		30 OVER ±0.3		APPROVED BY DATE MSASAO '04/02/10		MOLEX INCORPORATED			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-54548-039		SHEET NO. 2 OF 2	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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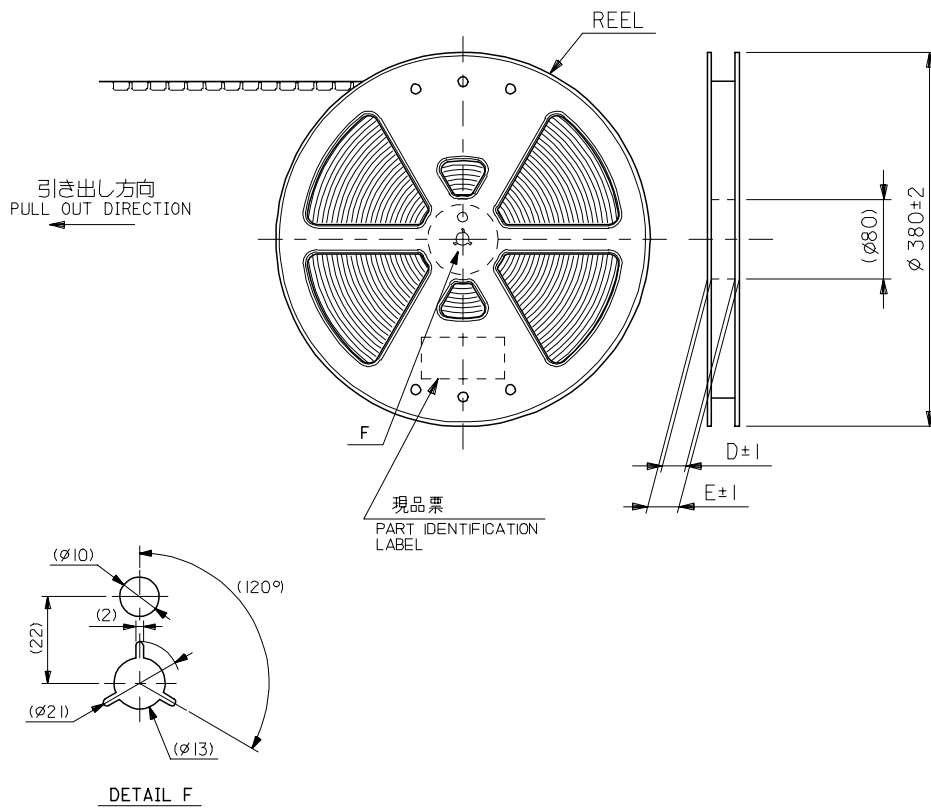
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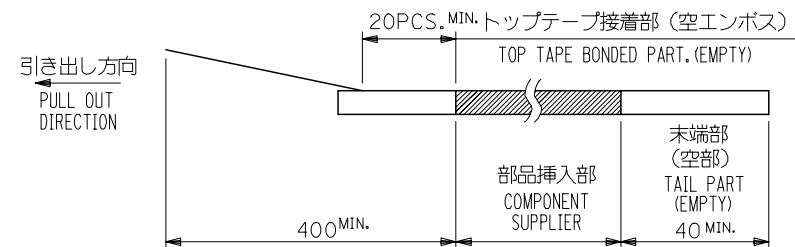
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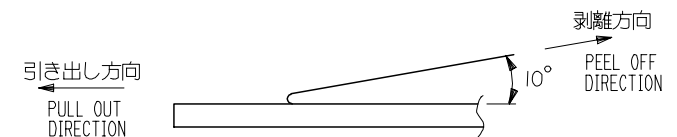


NOTES

- 製品詳細寸法については図面 SD-54548-039 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-039
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

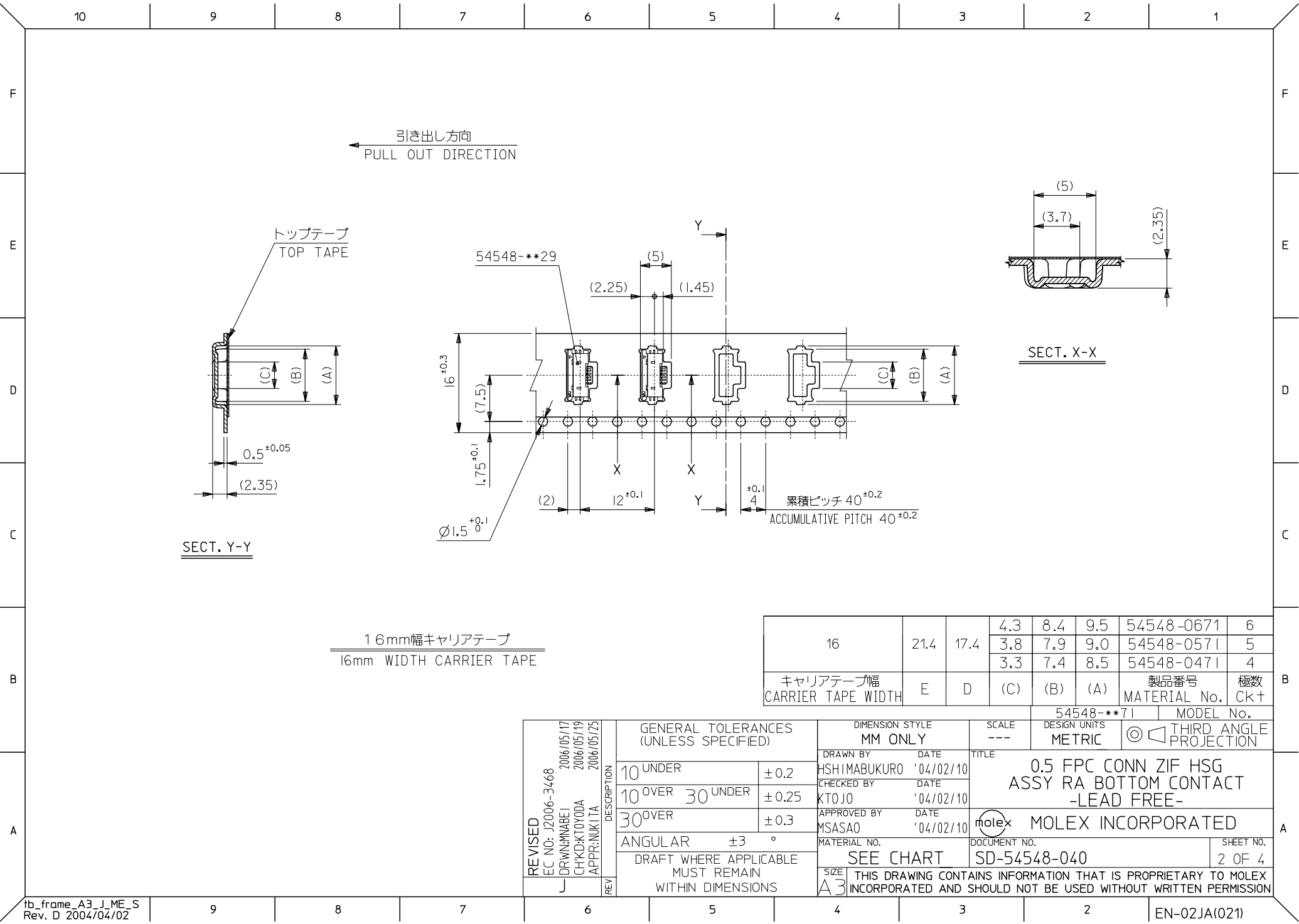


- トップテープの剥離強度：0.1N ～ 1.3N(10gf ～ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N(10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET , PE , PEF
リール(REEL)：ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 54548-**-91 の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-91 (SELECTIVE GOLD).

REVISED EC NO: J2006-3468 DRAWN:MABEI CHKD:KTOYODA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10					
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
J	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



16mm 幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	4.3	8.4	9.5	54548-0671	6
			3.8	7.9	9.0	54548-0571	5
			3.3	7.4	8.5	54548-0471	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	製品番号 MATERIAL No.	極数 Pin No.

REVISED EC NO: J2006-3468 DRAWN: NABEJ CHKD: KTOYODA APPR: NUKITA J	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/02/10					
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE '04/02/10	MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-040		2 OF 4		
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					





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